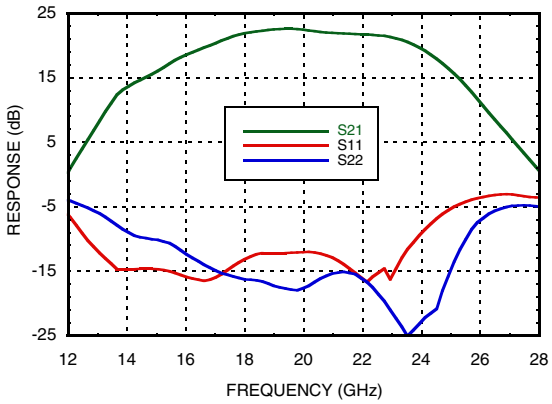
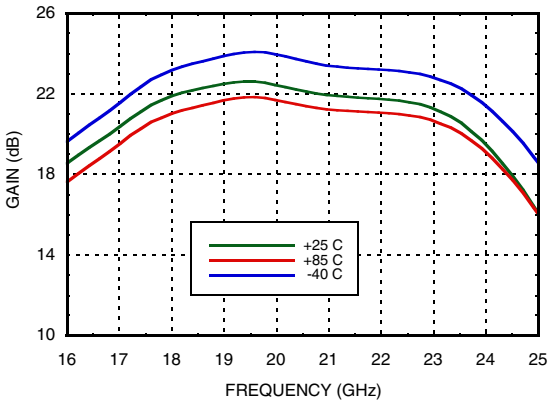
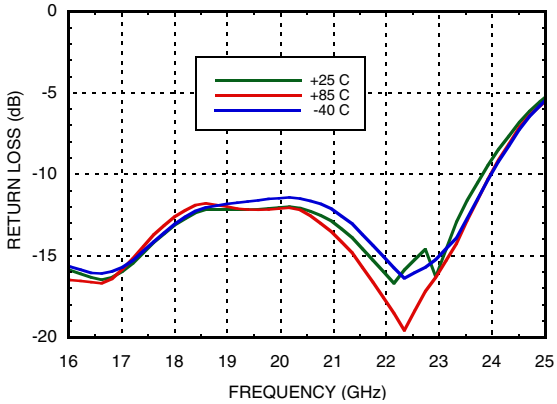
Broadband Gain & Return Loss



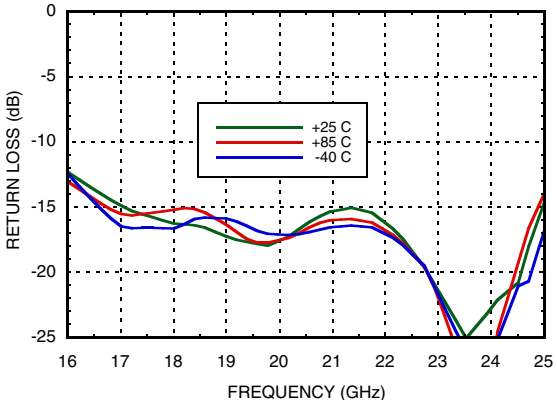
Gain vs. Temperature



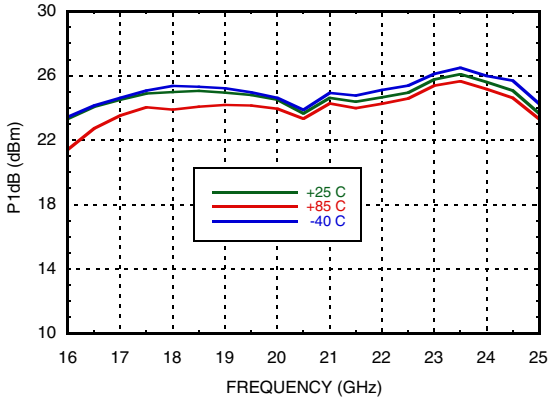
Input Return Loss vs. Temperature



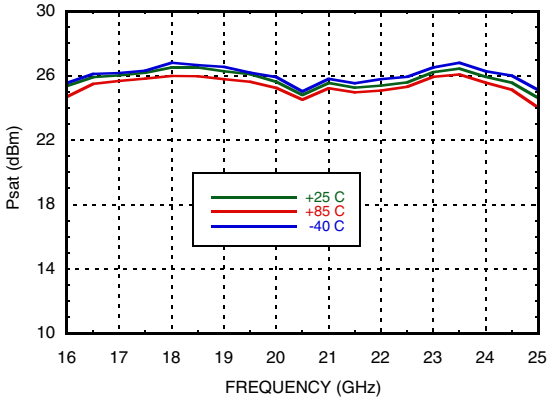
Output Return Loss vs. Temperature



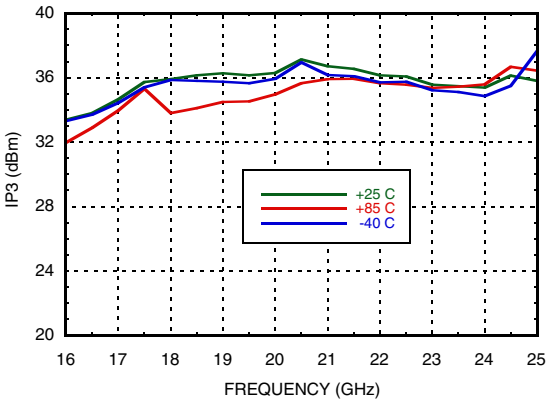
P1dB vs. Temperature



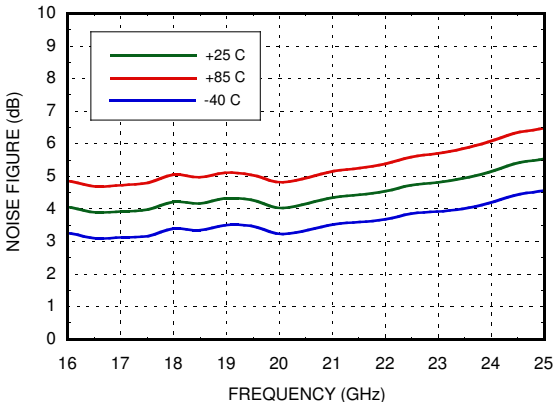
Psat vs. Temperature



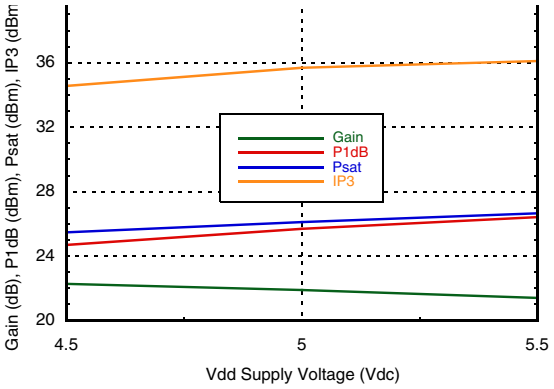
Output IP3 vs. Temperature



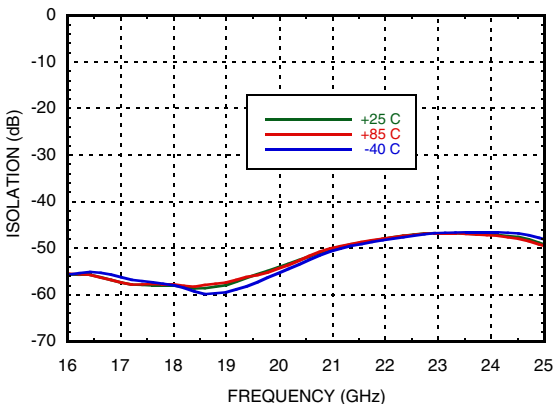
Noise Figure vs. Temperature



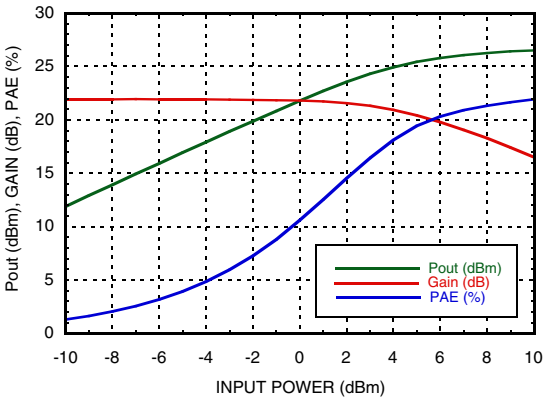
Gain, Power & OIP3 vs. Supply Voltage @ 23 GHz



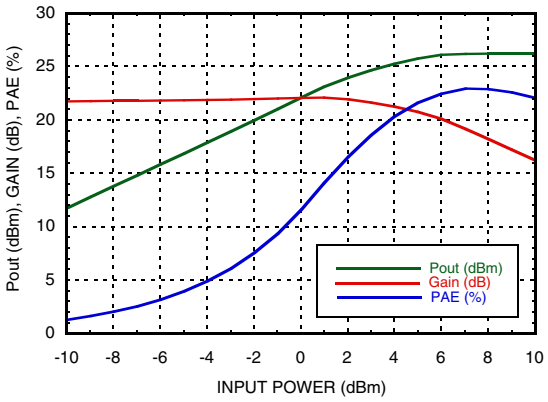
Reverse Isolation vs. Temperature



Power Compression @ 18 GHz



Power Compression @ 23 GHz



Absolute Maximum Ratings

Drain Bias Voltage (Vdd1, Vdd2, Vdd3)	+5.5 Vdc
Gate Bias Voltage (Vgg)	-4.0 to 0 Vdc
RF Input Power (RFIN)(Vdd = +5Vdc)	+10 dBm
Channel Temperature	175 °C
Continuous Pdiss (T= 85 °C) (derate 18 mW/°C above 85 °C)	1.62 W
Thermal Resistance (channel to ground paddle)	55.6 °C/W
Storage Temperature	-65 to +150 °C
Operating Temperature	-40 to +85 °C
ESD Sensitivity (HBM)	Class 1A

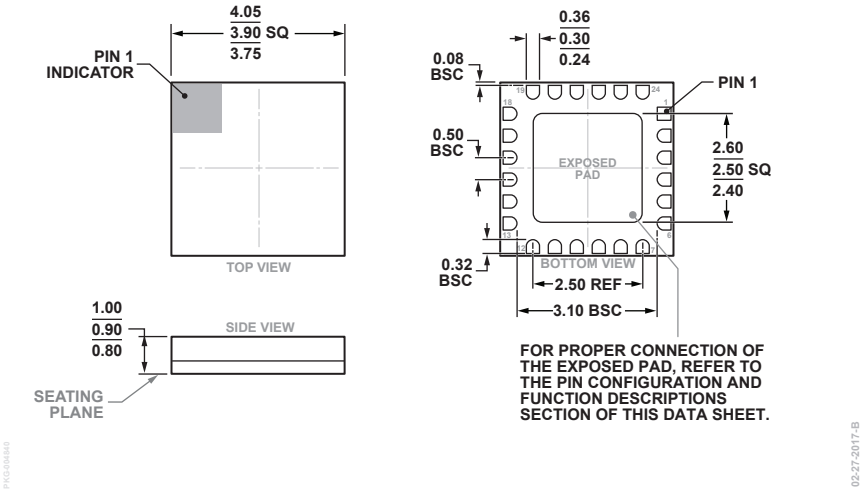
Typical Supply Current vs. Vdd

Vdd (Vdc)	Idd (mA)
+4.5	239
+5.0	250
+5.5	262

Note: Amplifier will operate over full voltage ranges shown above. Vgg adjusted to achieve Idd= 250 mA at +5V.

ELECTROSTATIC SENSITIVE DEVICE
OBSERVE HANDLING PRECAUTIONS

Outline Drawing



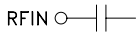
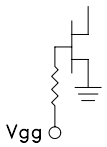
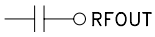
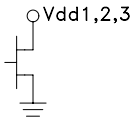
24-Terminal Ceramic Leadless Chip Carrier [LCC]
(E-24-1)
Dimensions shown in millimeters.

Package Information

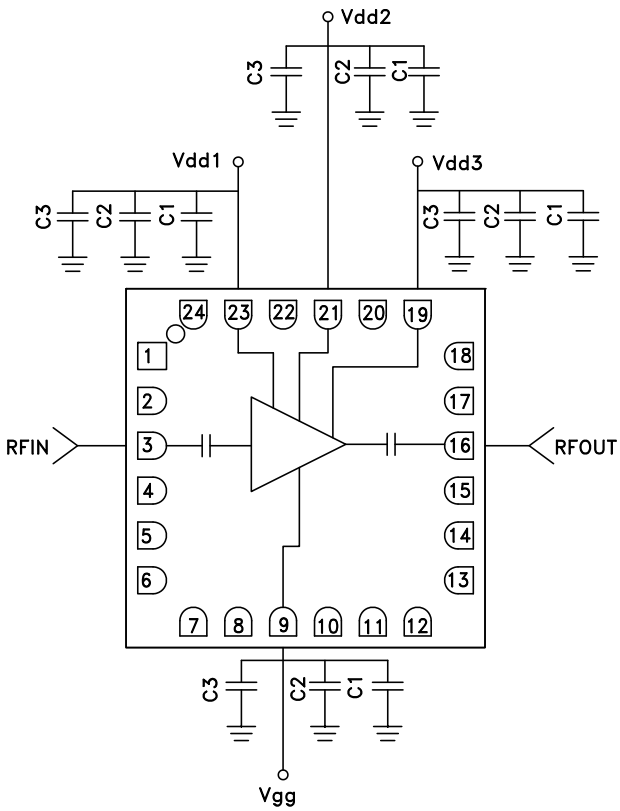
Part Number	Package Body Material	Lead Finish	MSL Rating	Package Marking [2]
HMC498LC4	Alumina, White	Gold over Nickel	MSL3 [1]	H498 XXXX

[1] Max peak reflow temperature of 260 °C
[2] 4-Digit lot number XXXX

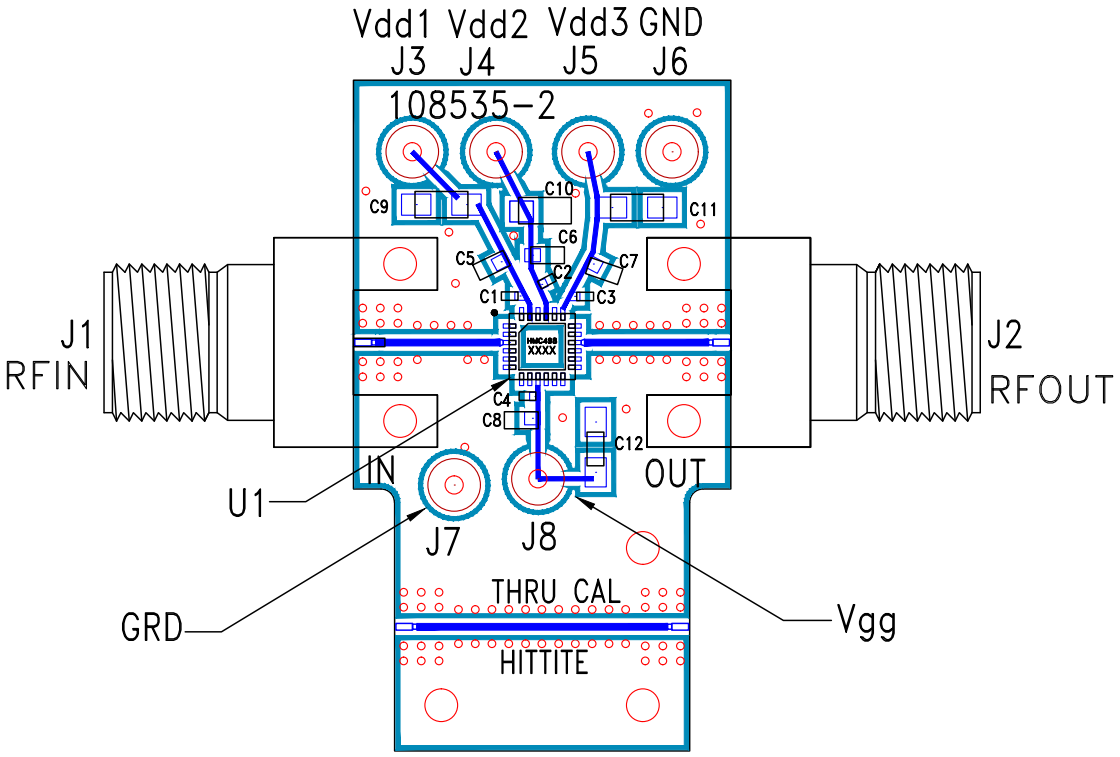
Pin Descriptions

Pin Number	Function	Description	Interface Schematic
1, 5 - 8, 10 - 14, 18, 20, 22, 24	N/C	These pins are not connected internally; however, all data shown herein was measured with these pins connected to RF/DC ground externally.	
2, 4, 15, 17	GND	Package bottom has an exposed metal paddle that must also be connected to RF/DC ground.	
3	RFIN	This pin is AC coupled and matched to 50 Ohms.	
9	Vgg	Gate control for amplifier. Adjust to achieve Id of 250 mA. Please follow "MMIC Amplifier Biasing Procedure" Application Note. External bypass capacitors of 100 pF, 1000 pF and 2.2 µF are required.	
16	RFOUT	This pin is AC coupled and matched to 50 Ohms.	
23, 21, 19	Vdd1, Vdd2, Vdd3	Power Supply Voltage for the amplifier. External bypass capacitors of 100 pF, 1000pF, and 2.2 µF are required.	

Application Circuit



Evaluation PCB



List of Materials for Evaluation PCB 108537 [1]

Item	Description
J1, J2	2.92 mm PC mount K-connector
J3 - J8	DC Pin
C1 - C4	100 pF capacitor, 0402 pkg.
C5 - C8	1,000 pF Capacitor, 0603 pkg.
C9 - C12	2.2µF Capacitor, Tantalum
U1	HMC498LC4 Amplifier
PCB [2]	108535 Evaluation PCB

[1] Reference this number when ordering complete evaluation PCB

[2] Circuit Board Material: Rogers 4350.

The circuit board used in this application should use RF circuit design techniques. Signal lines should have 50 Ohm impedance while the package ground leads and exposed paddle should be connected directly to the ground plane similar to that shown. A sufficient number of via holes should be used to connect the top and bottom ground planes. The evaluation board should be mounted to an appropriate heat sink. The evaluation circuit board shown is available from Analog Devices, upon request.